



INNOLAS
solutions

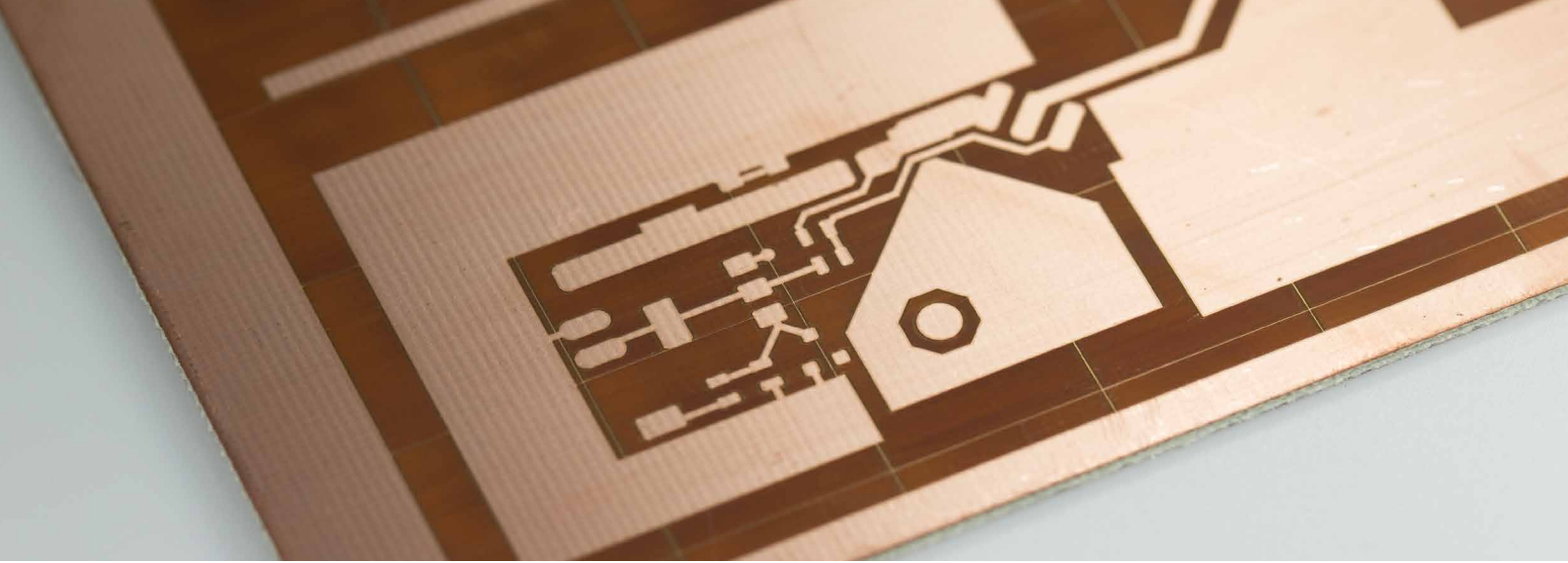


INNOVATION FOR THE
NEXT GENERATION



EXPEGO SPLIT AXIS MACHINE

VERSATILE **LASER SYSTEM**
FOR MICRO MATERIAL PROCESSING

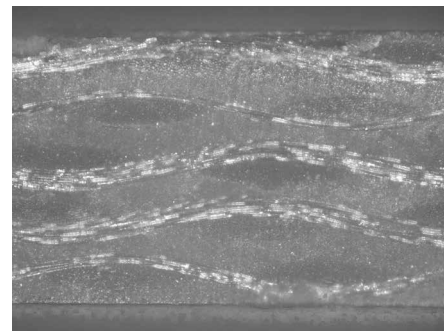
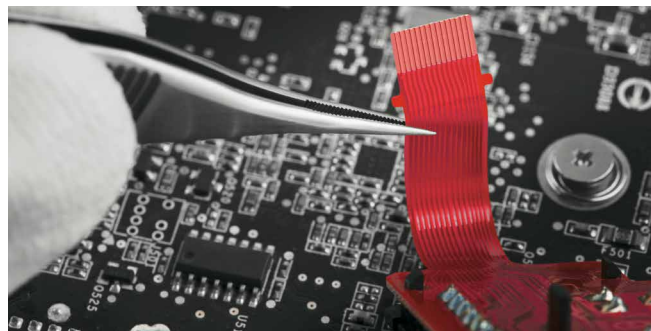
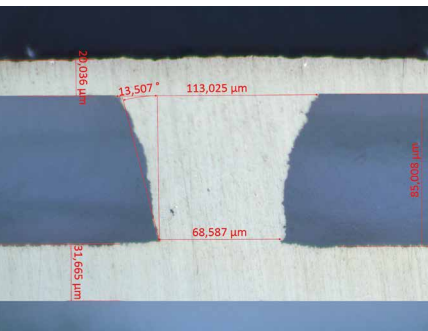


FEATURES

- ◆ High precise and ultrafast laser system
- ◆ Single or dual process head setup
- ◆ Integration of up to 3 laser systems
- ◆ In-situ scanner calibration
- ◆ InnoLas μ Vision system for high precise substrate alignment
- ◆ Operation system Windows 10 IoT
- ◆ Automatic laser to camera offset calibration

OPTIONS

- ◆ InnoLas Postprocessor – Import of CAD files (e.g. DXF, DWG, Gerber)
- ◆ SQL data base for process and event tracking
- ◆ MES interface (SECS, GEM, PV2, OPC, UA)
- ◆ Integrated process metrology
- ◆ Fully-automatic handling system
- ◆ INFINITY Scan to avoid stitching errors (simultaneous axis and scanner movement)



APPLICATIONS

Micro Via Drilling, Routing, Depaneling, Micro Structuring, Selective Ablation, Cavity Formation

ACCURACY

< +/- 5 μ m abs. (+/- .0 00019 Inches)
 < +/- 2 μ m repeatability (+/- .00 00078 Inches)

SUBSTRATES

Dimension up to 750 mm x 750 mm (29.5 x 29.5 Inches)
 Rigid-, flex-PCBs, ceramic, glass and advanced materials

AVAILABLE LASER SOURCES

Wavelength: 9.4, 10.6 μ m (CO₂), 1064, 1030, 532, 515, 355 nm
 Pulse: μ s, ns, ps, fs

DIMENSIONS

1750 x 2200 x 2600 mm (69 x 87 x 103 Inches)

